

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 30 December 2013 [Approved on 27 February 2026, 14:57 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.76%	Silicon	7440-21-3	100%
Die attach	Sn-Pb solder	0.78%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	34.7%	Carbon black	1333-86-4	0.6%
			Epoxy resin 89	26335-32-0	7.4%
			Quartz sand	60676-86-0	92%
Inner preparation	Cast aluminium alloys	2.02%	ALUMINUM, ELEMENTAL	7429-90-5	100%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.02%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	2.6%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	59.12%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TO-252AA/D-PAK_H_H-Free	Diode / Transistor Power	0.32	g

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